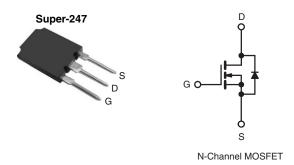
Vishay Siliconix

D Series Power MOSFET

PRODUCT SUMMARY				
V _{DS} (V) at T _J max.	V _{DS} (V) at T _J max. 550			
R _{DS(on)} max. at 25 °C (Ω)	V _{GS} = 10 V	0.130		
Q _g max. (nC) 125				
Q _{gs} (nC)	23			
Q _{gd} (nC)	37			
Configuration	ion Single			



FEATURES

- Optimal Design
 - Low Area specific On-Resistance
 - Low Input Capacitance (Ciss)
 - Reduced Capacitive Switching Losses
 - High Body Diode Ruggedness
 - Avalanche Energy Rated (UIS)
- · Optimal Efficiency and Operation
 - Low Cost
 - Simple Gate Drive Circuitry
 - Low Figure-Of-Merit (FOM): Ron x Qa
 - Fast Switching
- Material categorization: For definitions of compliance please see www.vishav.com/doc?99912

APPLICATIONS

- Consumer Electronics
 - Displays (LCD or Plasma TV
- Server and Telecom Power Supplies
 - SMPS
- Industrial
 - Welding, Induction Heating, Motor Drives
- · Battery Chargers

ORDERING INFORMATION			
Package	Super-247		
Lead (Pb)-free	SiHS36N50D-E3		

PARAMETER			SYMBOL	LIMIT	UNIT
Drain-Source Voltage			V _{DS}	500	
Gate-Source Voltage				± 30	V
Gate-Source Voltage AC (f > 1 Hz)			V_{GS}	30	
Continuous Drain Current /T 150 °C\	\/ at 10 \/	T _C = 25 °C	I _D	36	А
Continuous Drain Current (T _J = 150 °C)	V _{GS} at 10 V	$T_C = 25 ^{\circ}\text{C}$ $T_C = 100 ^{\circ}\text{C}$		23	
Pulsed Drain Current ^a			I _{DM}	112	
Linear Derating Factor				3.6	W/°C
Single Pulse Avalanche Energy ^b			E _{AS}	332	mJ
Maximum Power Dissipation			P_{D}	446	W
Operating Junction and Storage Temperature Range			T _J , T _{stg}	- 55 to + 150	°C
Drain-Source Voltage Slope	$T_{J} = 1$	T _J = 125 °C		24	V/ns
Reverse Diode dV/dt ^d			dV/dt	0.1	V/IIS
Soldering Recommendations (Peak Temperature) for 10 s				300°	°C

- a. Repetitive rating; pulse width limited by maximum junction temperature. b. $V_{DD}=50~V$, starting $T_J=25~^{\circ}C$, L=2.3~mH, $R_g=25~\Omega$, $I_{AS}=17~A$.
- c. 1.6 mm from case.
- d. $I_{SD} \le I_D$, starting $T_J = 25$ °C.



Vishay Siliconix

THERMAL RESISTANCE RATINGS					
PARAMETER	SYMBOL	TYP.	MAX.	UNIT	
Maximum Junction-to-Ambient	R _{thJA}	-	40	°C/W	
Maximum Junction-to-Case (Drain)	R_{thJC}	-	0.28		

PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static					•		
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		500	-	-	V
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	Reference	to 25 °C, I _D = 250 μA	-	0.52	-	V/°C
Gate Threshold Voltage (N)	V _{GS(th)}	V _{DS} =	= V _{GS} , I _D = 250 μA	3.0	-	5.0	V
Gate-Source Leakage	I _{GSS}		V _{GS} = ± 30 V	-	-	± 100	nA
-		V _{DS} =	= 500 V, V _{GS} = 0 V	-	-	1	
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 400 \	/, V _{GS} = 0 V, T _J = 125 °C	-	-	10	μA
Drain-Source On-State Resistance	R _{DS(on)}	V _{GS} = 10 V	I _D = 18 A	-	0.105	0.130	Ω
Forward Transconductancea	9 _{fs}		= 50 V, I _D = 18 A	-	12.8	_	S
Dynamic						l	
Input Capacitance	C _{iss}	T	V _{GS} = 0 V,	-	3233	_	
Output Capacitance	C _{oss}		$V_{DS} = 100 \text{ V},$	-	285	-	=
Reverse Transfer Capacitance	C _{rss}	1	f = 1 MHz		25	-	
Effective Output Capacitance, Energy Related ^a	C _{o(er)}	V _{GS} = 0 V, V _{DS} = 0 V to 400 V		-	240	-	pF
Effective Output Capacitance, Time Related ^b	C _{o(tr)}			-	352	-	
Total Gate Charge	Qg			-	83	125	
Gate-Source Charge	Q _{gs}	$V_{GS} = 10 \text{ V}$ $I_D = 18 \text{ A}, V_{DS} = 400 \text{ V}$		-	23	-	nC
Gate-Drain Charge	Q _{gd}			-	37	-	
Turn-On Delay Time	t _{d(on)}			-	33	66	
Rise Time	t _r	V_{DD} = 400 V, I_{D} = 18 A, V_{GS} = 10 V, R_{g} = 9.1 Ω		1	89	134	ns
Turn-Off Delay Time	$t_{d(off)}$			-	79	119	
Fall Time	t _f				68	102	
Gate Input Resistance	R_g	f = 1 MHz, open drain		-	1.8	-	Ω
Drain-Source Body Diode Characteristic	s						
Continuous Source-Drain Diode Current	I _S	MOSFET sym showing the	MOSFET symbol showing the		-	36	
Pulsed Diode Forward Current	I _{SM}	integral reverse p - n junction diode		-	-	144	Α
Diode Forward Voltage	V _{SD}	T _J = 25 °C, I _S = 18 A, V _{GS} = 0 V		-	-	1.2	V
Reverse Recovery Time	t _{rr}			-	490	-	ns
Reverse Recovery Charge	Q _{rr}		5 °C, I _F = I _S = 18 A,	-	8.2	-	μC
Reverse Recovery Current	I _{RRM}	dl/dt = 100 A/μs, V _R = 20 V		_	31	_	A

Notes

- a. $C_{oss(er)}$ is a fixed capacitance that gives the same energy as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS} . b. $C_{oss(tr)}$ is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS} .



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

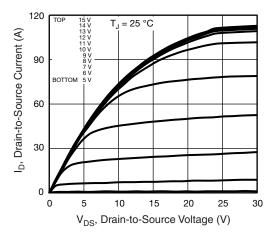


Fig. 1 - Typical Output Characteristics

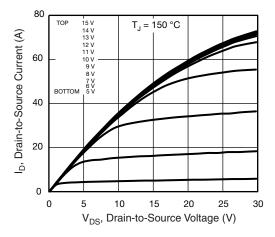


Fig. 2 - Typical Output Characteristics

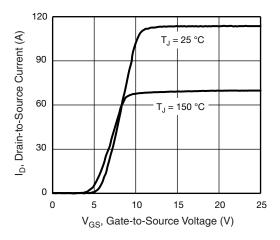


Fig. 3 - Typical Transfer Characteristics

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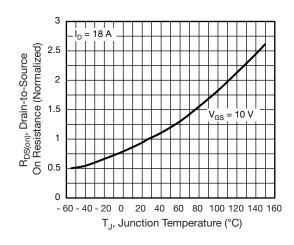


Fig. 4 - Normalized On-Resistance vs. Temperature

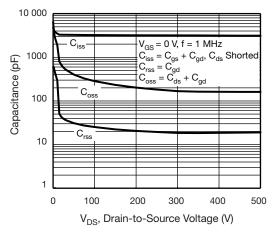


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

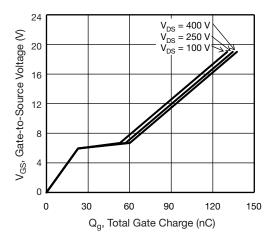


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage



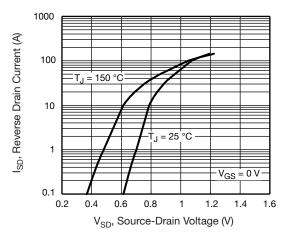


Fig. 7 - Typical Source-Drain Diode Forward Voltage

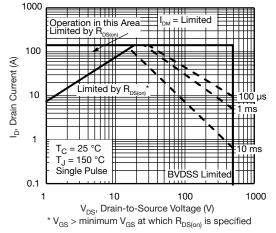


Fig. 8 - Maximum Safe Operating Area

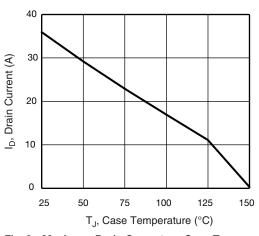


Fig. 9 - Maximum Drain Current vs. Case Temperature

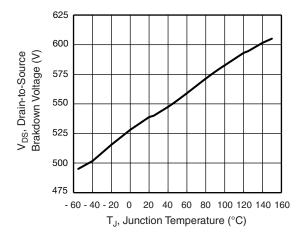


Fig. 10 - Temperature vs. Drain-to-Source Voltage

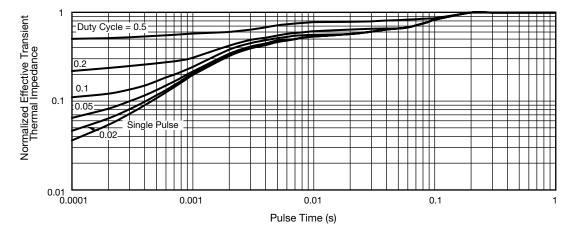


Fig. 11 - Normalized Thermal Transient Impedance, Junction-to-Case



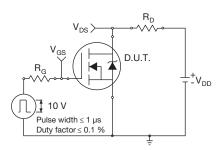


Fig. 12 - Switching Time Test Circuit

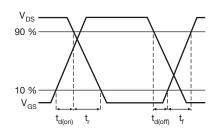


Fig. 13 - Switching Time Waveforms

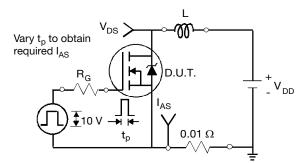


Fig. 14 - Unclamped Inductive Test Circuit

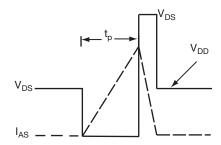


Fig. 15 - Unclamped Inductive Waveforms

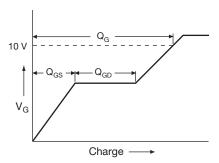


Fig. 16 - Basic Gate Charge Waveform

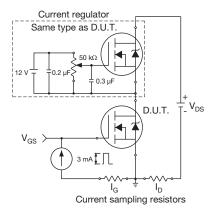
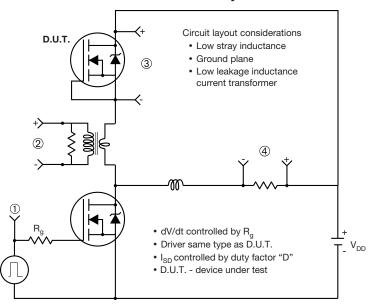


Fig. 17 - Gate Charge Test Circuit



Peak Diode Recovery dV/dt Test Circuit



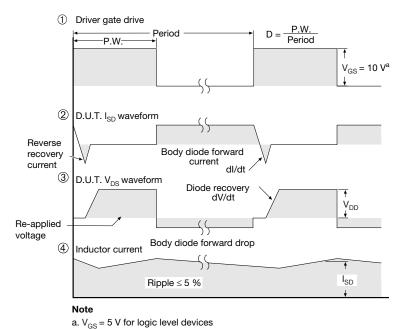


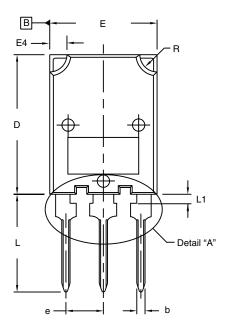
Fig. 18 - For N-Channel

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see www.vishay.com/ppg?91514.

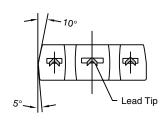




TO-274AA (HIGH VOLTAGE)







MILLIMETERS

MAX.

5.30

2.50

2.65

1.60

2.20

3.25

1.20

20.80

MIN.

4.70

1.50

2.25

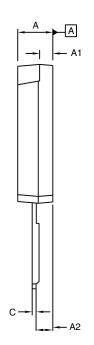
1.30

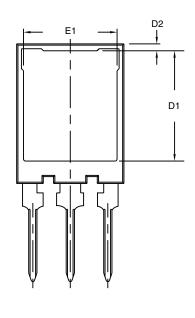
1.80

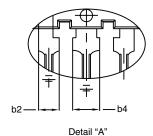
3.00

0.80

19.80







Scale: 2:1

:S	
MAX.	
0.209	
0.098	
0.104	
0.063	
0.087	
0.128	
0.047	
0.819	

INCHES

MIN.

0.185

0.059

0.089

0.051

0.071

0.118

0.031

0.780

	MILLIN	IETERS	INCHES		
DIM.	MIN.	MAX.	MIN.	MAX.	
D1	15.50	16.10	0.610	0.634	
D2	0.70	1.30	0.028	0.051	
Е	15.10	16.10	0.594	0.634	
E1	13.30	13.90	0.524	0.547	
е	5.45	BSC	0.215 BSC		
L	13.70	14.70	0.539	0.579	
L1	1.00	1.60	0.039	0.063	
R	2.00	3.00	0.079	0.118	

ECN: S-82247-Rev. A, 06-Oct-08 DWG: 5975

. .

DIM.

Α

Α1

A2

b

b2

b4

- 1. Dimensioning and tolerancing per ASME Y14.5M-1994.
- 2. Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outer extremes of the plastic body.
- 3. Outline conforms to JEDEC outline to TO-274AA.



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Vishay

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